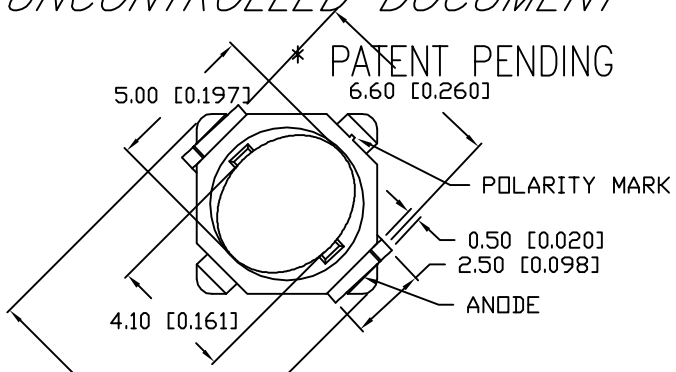
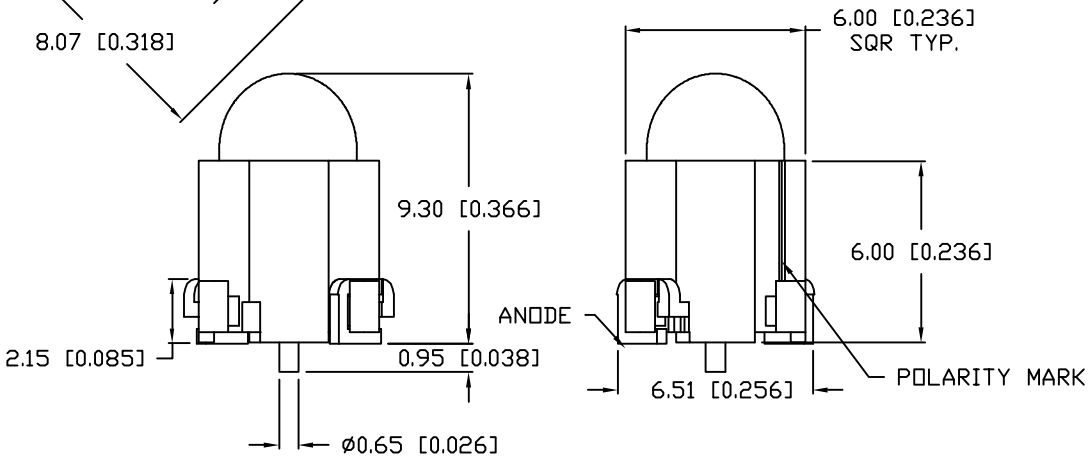
UNCONTROLLED DOCUMENT

PART NUMBER	REV.
SML-H150E5UPGD/NC	



CAUTION: STATIC SENSITIVE DEVICE
FOLLOW PROPER E.S.D. HANDLING PROCEDURES WHEN WORKING WITH THIS PART.



ELECTRO-OPTICAL CHARACTERISTICS T_A=25°C I_f= 20MA

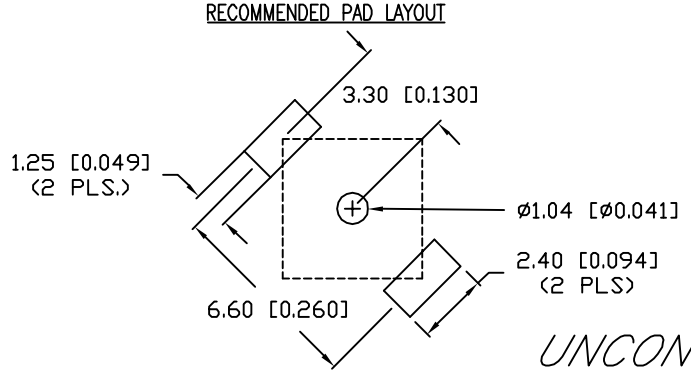
PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		520		nm	
FORWARD VOLTAGE	2.8		3.4	V_f	
REVERSE VOLTAGE	5.0			V_r	I_r=100µA
AXIAL INTENSITY*		REFER TO CHART		mcd	I_f = 20MA
VIEWING ANGLE (X)		60		2x theta	
VIEWING ANGLE (Y)		30		2x theta	
EMITTED COLOR:	GREEN				
EPOXY LENS FINISH:	GREEN DIFFUSED				

LIMITS OF SAFE OPERATION AT 25°C PER DIE

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT**	100	mA
STEADY CURRENT	20	mA
POWER DISSIPATION	80	mW
DERATE FROM 25°C	-1.2	mW/°C
OPERATING TEMP.	-30 TO +80	°C
STORAGE TEMP.	-40 TO +100	°C

**1/10 DUTY CYCLE, 0.1mS PULSE WIDTH

RECOMMENDED PAD LAYOUT



*AXIAL INTENSITY BINS

BIN	INTENSITY@20mA	
	MIN (mcd)	MAX (mcd)
9	2800	3850
0	3850	5200

NOTES:
1. PART USES ROUND REFLECTOR CUP WITH NO SILICONE ENDCAPSULATION OVER DICE.
2. NO BIN CODE ON EACH BAG AS PARTS ARE MIXED BINS IN A BAG.

Pb

UNCONTROLLED DOCUMENT

*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030). MIN=+DECIMAL PRECISION -0.00 MAX.= +0.00 -DECIMAL PRECISION

REV.	PART NUMBER	CONFIDENTIAL INFORMATION	LUMEX	290 E. HELEN ROAD PALATINE, IL 60067-6976 PHONE: +1.847.359.2790 US WEB: www.lumex.com TW WEB: www.lumex.com.tw
	SML-H150E5UPGD/NC	THE INFORMATION CONTAINED IN THIS DOCUMENT IS THE PROPERTY OF LUMEX INC. EXCEPT AS SPECIFICALLY AUTHORIZED IN WRITING BY LUMEX INC., THE HOLDER OF THIS DOCUMENT SHALL KEEP ALL INFORMATION CONTAINED HEREIN CONFIDENTIAL AND SHALL PROTECT SAME IN WHOLE OR IN PART FROM DISCLOSURE AND DISSEMINATION TO ALL THIRD PARTIES.	Creating LED and LCD Solutions Together™	
	5X4mm ELLIPTICAL SURFACE MOUNTED DOME LED, 520nm PURE GREEN LED, GREEN DIFFUSED.	RELIABILITY NOTE OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.		

DRAWN BY:	CHECKED BY:	APPROVED BY:	DATE: 12.01.09 PAGE: 1 OF 2 SCALE: N/A
JN			